## **DSA7U01**

### Silicon PNP epitaxial planar type

For Low-frequency amplifier

#### ■ Features

- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

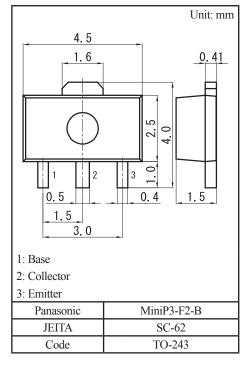
#### ■ Marking Symbol: 4H

#### Packaging

DSA7U01×0L Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-100	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-100	V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-5	V
Collector current	$I_{C}$	- 0.5	A
Peak collector current	I <sub>CP</sub>	-1	A
Collector power dissipation *1	P <sub>C</sub>	1	W
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub> -40 to +8:		°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C



Note) \*1: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Absolute maximum rating without heat sink for  $P_C$  is  $0.5~\mathrm{W}$ 

#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

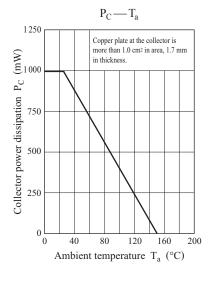
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -100 \mu\text{A}, I_{\rm B} = 0$	-100			V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = -10 \mu\text{A}, I_{\rm C} = 0$	-5			V	
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = -10 \text{ V}, I_{C} = -150 \text{ mA}$	90		220		
	h <sub>FE2</sub>	$V_{CE} = -5 \text{ V}, I_{C} = -500 \text{ mA}$	50			_	
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		-0.2	-0.6	V	
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		- 0.9	-1.2	V	
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_{C} = -50 \text{ mA}$		120		MHz	
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			30	pF	

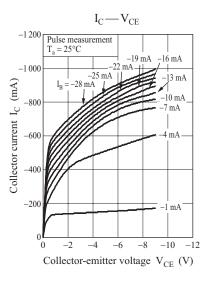
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

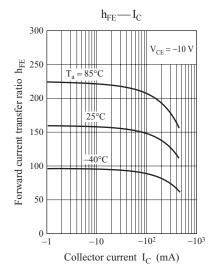
- 2. \*1: Pulse measurement
  - \*2: Rank classification

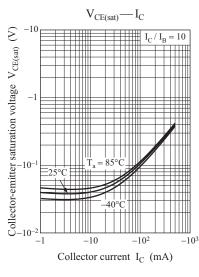
Code	Q	R	0
Rank	Q	R	No-rank
$h_{\mathrm{FE1}}$	90 to 155	130 to 220	90 to 220
Marking Symbol	4HQ	4HR	4H

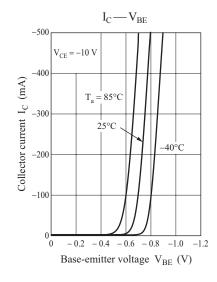
Product of no-rank is not classified and have no marking symbol for rank.

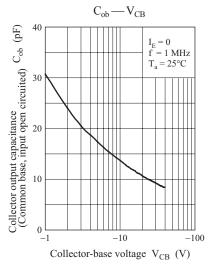


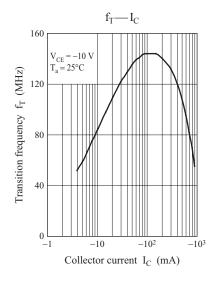


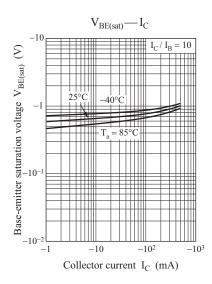






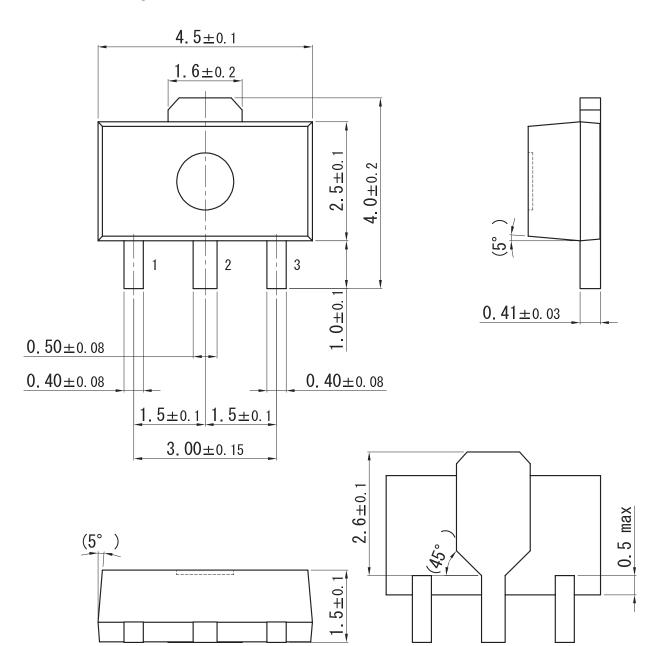




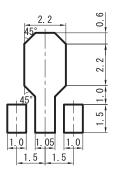


## MiniP3-F2-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)



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